

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

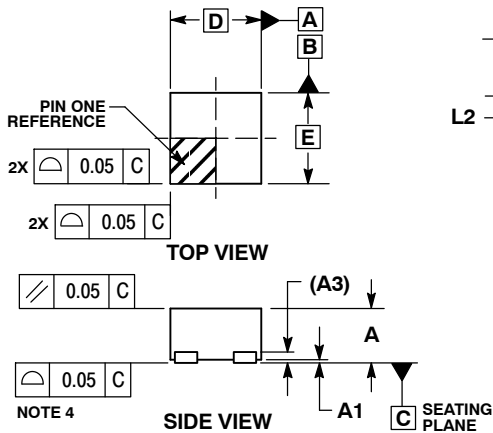
ON Semiconductor®



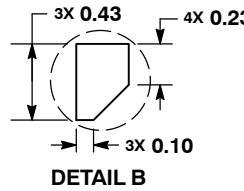
SCALE 4:1

UDFN4 1.0x1.0, 0.65P
CASE 517BR-01
ISSUE O

DATE 27 OCT 2010



DETAIL A



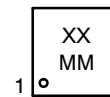
DETAIL B

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

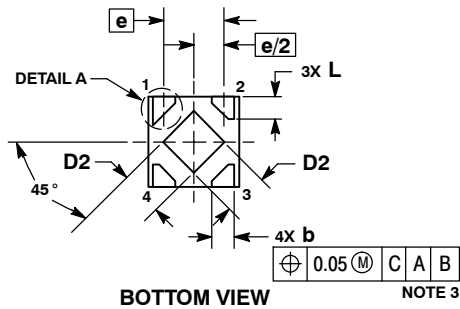
DIM	MILLIMETERS	
	MIN	MAX
A	---	0.60
A1	0.00	0.05
A3	0.10	REF
b	0.20	0.30
D	1.00	BSC
D2	0.43	0.53
E	1.00	BSC
e	0.65	BSC
L	0.20	0.30
L2	0.27	0.37
L3	0.02	0.12

GENERIC MARKING DIAGRAM*



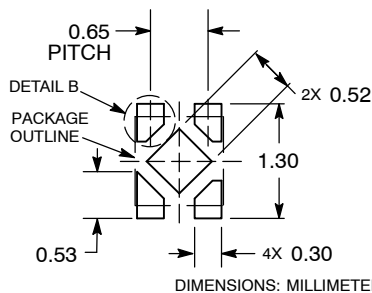
XX = Specific Device Code
MM = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.



BOTTOM VIEW

RECOMMENDED MOUNTING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		
DESCRIPTION:	UDFN4, 1.0X1.0, 0.65P	PAGE 1 OF 2

